

· Abstract

A method and the associated device are described for attaching at least one micromechanical chip in a housing which is

5 optically transparent to radiation of at least one predefined transmission wavelength, in which

- an adhesive layer is applied between the chip and the housing and
- the adhesive layer is irradiated through the housing
- 10 using radiation of the transmission wavelength for the purpose of curing.

(Figure 3)